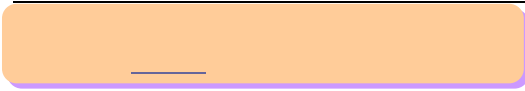


有铅

Sn50/Pb50 SnPbBi

- 1 0.4mm
- 2 12
- 3
- 4
- 5 “ --- ” “ ”
- 6 PCB
- 7 ICT
- 8 Paste in hole

	ROL1	J-STD-004
	0.2wt%	
(SIR)	1×10^{13}	25mil
	1×10^{12}	40 90%RH 96Hrs
	1×10^5	
		IPC-TM-650
		IPC-TM-650
		In house
	85~91wt% ± 0.5	
	9~15wt% ± 0.5	
	200 Pa.s ± 10% Malcolm (10rpm,25)	T3,90% metal for printing
	80 Pa.s ± 10% Malcolm (10rpm,25)	T4,87% metal for syringe
	0.55 ± 0.05	In house
	90%	Copper plate(Sn63,90%metal)
		J-STD-005
		In house
Vs	48gF 0	IPC-TM-650 ± 5%
	56gF 2	
	68gF 4	
	44gF 8	
	12	In house
		0~10



1

T3 mesh -325/+500 25~45μ m

Fine pitch

2

1) “ ”

0~10

200

4

2) “ ”

3

1 ;

(适当的搅拌时间因搅拌方式、装置及环境温度等因素而有所不同，应在事前多做试验来确定)。

3



有铅免洗

0.4mm

0.12mm



有铅免洗

80%

	60 ~ 90HS
	45 ⁰ ~ 60 ⁰
	2 ~ 4 × 10 ⁵ pa
	20 ~ 40mm/sec 15 ~ 20mm/sec 50 ~ 100mm/sec
	25 ± 3 40 ~ 70%



*

*

*

PCB

PCB

A5

200g

B5

300g

A4

400g

4

4

5

6

此有铅



500g

PE

20

35



0 ~10

•

•

0

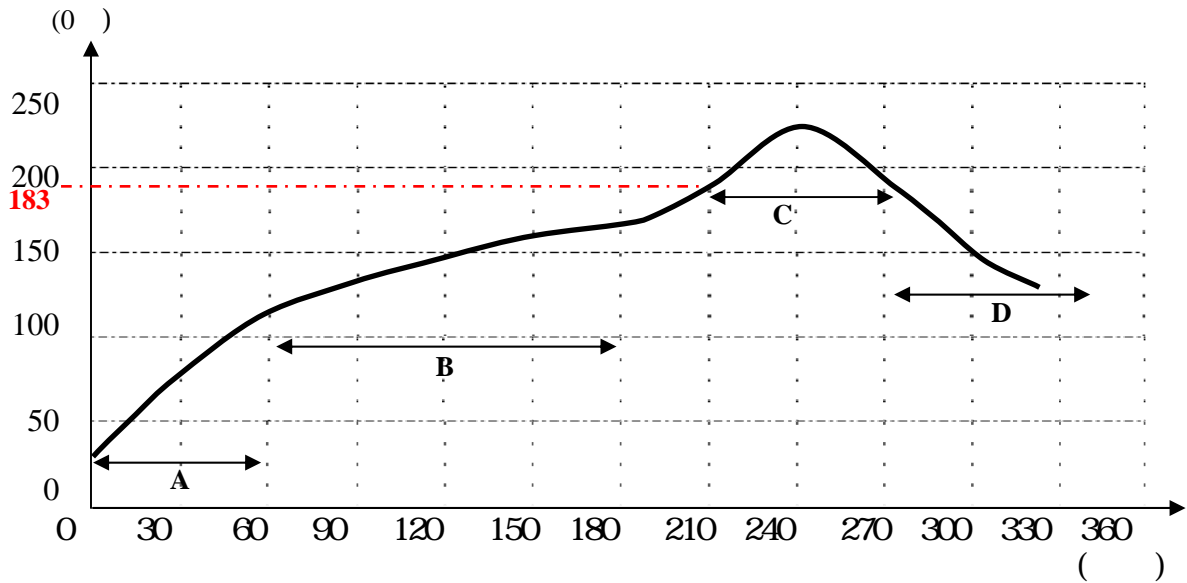
6



MSDS

有铅

Sn50/Pb50 SnPbBi



A. _____ 25~33%

* 1.0~3.0 /
*

B. _____ 33~50%

* 150~200 60~90 PCB 1.5 /

C. _____

* 230~245 183 70~90 Important 200 50~65
*
*

D. _____

* 4 75
*
*

➤
➤
➤

“ _ ” “ _ ”